

Unconfirmed Meeting Minutes: IEEE 802.3 New Ethernet Applications Ad Hoc Interim Meeting

May 21, 2019
Salt Lake City, UT, USA
Prepared by Jon Lewis

Tuesday, May 21, 2019

Meeting Chaired by Jon Lewis, Vice-Chair NEA

Meeting called to order at approximately 7:03 pm.

Presentation #1 – General Information & Agenda

Presenter: Jon Lewis

URL: http://www.ieee802.org/3/ad_hoc/ngrates/public/18_05/agenda_nea_01_0518.pdf

Vice-Chair reviewed agenda for meeting.

Motion #1: Move to approve the agenda as shown

M: George Zimmerman S: Bob Voxx

Motion passed by voice without opposition

Motion #1: Move to approve the minutes as posted:

http://www.ieee802.org/3/ad_hoc/ngrates/public/19_03/minutes_nea_0319_unapproved.pdf

http://www.ieee802.org/3/ad_hoc/ngrates/public/calls/19_0415/minutes_nea_190415_unapproved.pdf

http://www.ieee802.org/3/ad_hoc/ngrates/public/calls/19_0416/minutes_nea_190416_unapproved.pdf

M: Marek Hajduczenia S: Natalie Wienckowski

Motion passed by voice without opposition

Individuals in the room introduced themselves.

Vice-Chair reviewed Pre-PAR Patent policy.

Vice-Chair showed IEEE802 Meetings Participation slide.

Chair reviewed IEEE 802.3 NEA Ad Hoc information, Ground Rules, Important bylaws, Rules & References, Overview of NEA Ad hoc, and requesting a CFI in IEEE 802.3.

Presentation #2 – Draft - CFI Consensus Presentation - Automotive Optical Multi Gig

Presenter – Carlos Pardo, KDPOF

URL: http://www.ieee802.org/3/ad_hoc/ngrates/public/19_05/pardo_nea_01a_0519.pdf

Questions regarding clarity were asked and answered.

Presentation #3 – Draft - CFI Consensus Presentation -Improving PTP Timestamping Accuracy on Ethernet Interfaces

Presenter – Richard Tse, Microchip

URL: http://www.ieee802.org/3/ad_hoc/ngrates/public/19_05/tse_nea_01a_0519.pdf

It was noted that the deadline for the CFI needs to be made 35 days in advance of the July Plenary which is rapidly approaching.

Presentation #4 – Possible CFI for 10SPE Multidrop Enhancements

Presenter – Peter Jones, Cisco

URL: http://www.ieee802.org/3/ad_hoc/ngrates/public/19_05/jones_nea_01_0519.pdf

General Discussion on the scope defined and who to contact to assist in the CFI preparation.

Meeting adjourned ≈ 8:43 pm

Attendees

IEEE 802.3 NEA IEEE 802.3 May 2019 Interim

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Last Name	First Name	Employer	Affiliations
Abramson	David	TI	TI
Aono	Michikazu	Yazaki	Yazaki
Baggett	Tim	Microchip	Microchip
Berck	Wang	Center Networks	Center Networks
Bhagwat	Gitesh	Analog Devices	Analog Devices
Bie		Robert Bosch	Robert Bosch
Brandt	David	Rockwell Automation	Rockwell Automation
Brownlee	Phillip	Self	TDK
Canchi	Radhakrishna	Kyocera Intl. Inc.	Kyocera Intl. Inc.
Chalupsky	David	Intel	Intel
Chen	David	AOI	AOI
Choudhury	Mabud	OFS	OFS
Dupuis	Marc	Web Industries	Web Industries
Ferretti	Vincent	Corning	Corning
Fritsche	Matthias	Harting	Harting
Gorshe	Steve	Microsemi	Microsemi
Graber	Steffen	Pepperl & Fuchs	Pepperl & Fuchs
Grant	Mark	HPE	HPE
Grau	Olaf	Robert Bosch	Robert Bosch
Hajduczenia	Marek	Charter	Charter
Hess	Dave	Cord Data	Cord Data
Hyakutake	Yoisuhiro	Adamant Namiki Precision Jewel	Adamant Namiki Precision Jewel
Isono	Hideki	Fujitsu Optical Components	Fujitsu Optical Components
Jones	Chad	Cisco	Cisco

IEEE 802.3 NEA
IEEE 802.3 May 2019 Interim

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Last Name	First Name	Employer	Affiliations
Kagami	Manabu	NITech	NITech
Kim	Inho	Marvell Semiconductor	Marvell Semiconductor
Koczwara	Wojciech	Rockwell Automation	Rockwell Automation
Kondo	Taiji	Megachips	Megachips
Kumado	Takato	Yazaki	Yazaki
Lackner	Hans	QoSCom	QoSCom
Law	David	HPE	HPE
Lewis	Jon	Dell EMC	Dell EMC
Lin	Karen	Lighthouse Logic	Lighthouse Logic
Lingle, Jr.	Robert	OFS	OFS
Malicoat	David	Malicoat Networking Solutions / Senko	Malicoat Networking Solutions / Senko
Masuda	Takeo	OITDA/PETRA	OITDA/PETRA
McMillan	Larry	Western Digital	Western Digital
Nicholl	Shawn	Xilinx	Xilinx
Noll	Kevin	Tibit Communications	Tibit Communications
Pardo	Carlos	KDPOF	KDPOF
Pham	Phong	US Conec Ltd	US Conec Ltd
Pozzebon	Dino	Microsemi	Microsemi
Reinhard	Michael	SEI ANTech-Europe	SEI ANTech-Europe
Renteria	Victor	Bel Fuse Inc.	Bel Fuse Inc.
Shariff	Masood	Commscope	Commscope
Shitno	Masato	Furukawa Electric	Furukawa Electric
Stewart	Heath	ADI	ADI
Swanson	Steve	Corning	Corning
Takahara	Tomoo	Fujitsu Laboratories	Fujitsu Laboratories
Tao	Bu	Center Networks	Center Networks
Tellas	Ron	Belden	Belden
Terada	Masaru	OFS	OFS
Tse	Richard	Microchip	Microchip
Voss	Bob	Panduit Corp.	Panduit Corp.
Wang	Xinyuan	Huawei	Huawei
Wienckowski	Natalie	GM	GM
Woods	Jordon	Analog Devices	Analog Devices

IEEE 802.3 NEA
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Last Name	First Name	Employer	Affiliations
Wucher	Markus	Endress+Hauser	Endress+Hauser
Yoshihiro	Niihara	Fujikura	Fujikura
Zimmerman	George	CME Consulting	Commscope, Aquantia, CME Consulting, Cisco, ADI, BMW, APL Group, SensTek